REVISION E	
9/7/2011	ECN-162220

RECOMMENDED PCB LAYOUT FOR UPS-XX-XX.X-XX-X-V-XX-FOOTPRINT

DESIGNED & DIMENSIONED IN MILLIMETERS[INCHES]

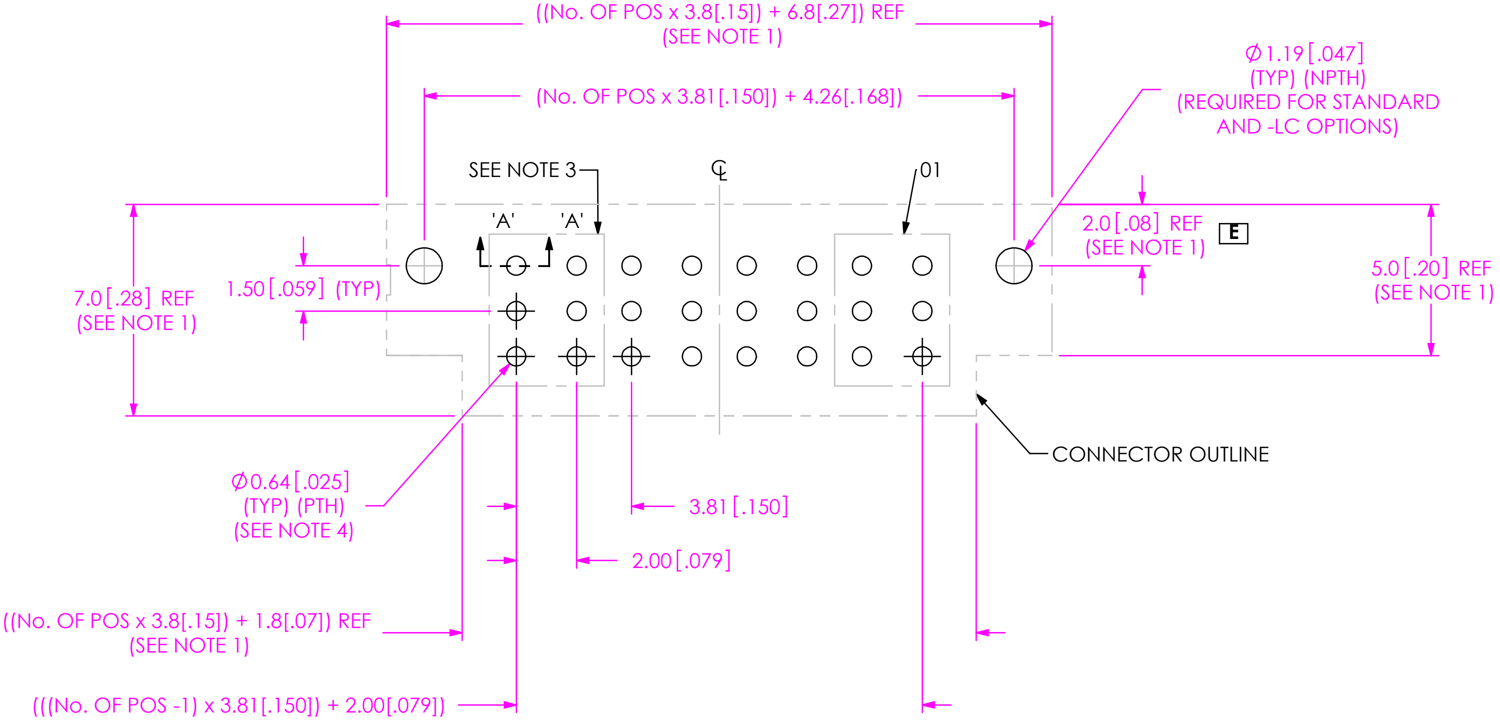

FIG 1
(UPS-04-XX.X-XX-X-V-XX SHOWN)

NOTES:
1. CONNECTOR ENVELOPE DIMENSIONS. OTHER COMPONENTS PLACED ON PCB SHALL AVOID THIS ZONE.
2. ALL DIMENSIONS SYMMETRIC ABOUT THE CENTERLINE.
3. EACH GROUP HOLDS ONE POWER PIN
4. VIAS FOR PRESS-FIT PRODUCT MUST CONFORM TO SPECIFICATIONS SHOWN IN SECTION "A-A"

F:\DWG\MISC\Mktg\Footprnt\UPS-XX-XX.X-XX-X-V-XX-FOOTPRINT.SLDDRW

520 PARK EAST BLVD, NEW ALBANY, IN 47150
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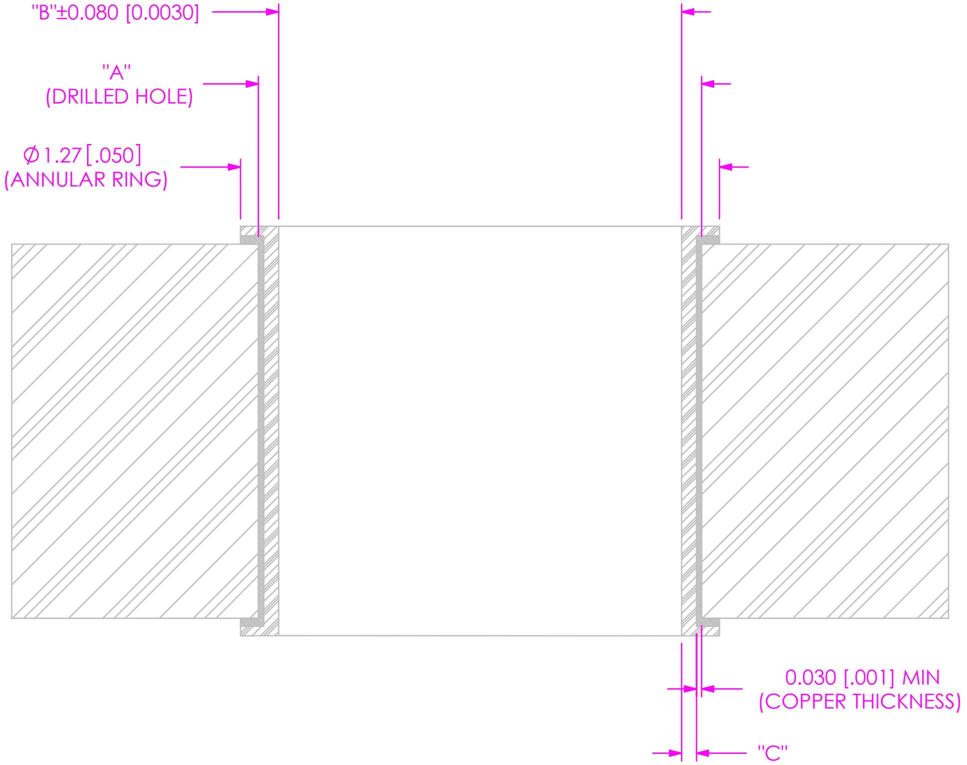
REVISION E



SECTION 'A' - 'A'
(SEE NOTE 4)

TABLE 1			
PLATING	"A"+/-.001	"B"+/-.003	"C"
HOT AIR LEVEL TIN	0.74 [0.029]	0.64 [0.025]	0.015 [.006] MAX TIN
ELECTROLESS GOLD OVER NICKEL	0.74 [0.029]	0.64 [0.025]	.0025 - .0076 [.0001 - .0003] NICKEL / .00005 - .00020 (.000002 - .000008) GOLD
ORGANIC SURFACE PROTECTANT COPPER	0.71 [0.028]	0.64 [0.025]	NA

PROPRIETARY NOTE

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DO NOT SCALE DRAWING

SHEET SCALE: 4:1

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DESCRIPTION:
MICRO POWER FOOTPRINT

DWG. NO.
UPS-XX-XX.X-XX-X-V-XX-FOOTPRINT

BY: B RAY 08/25/2008 SHEET 2 OF 2